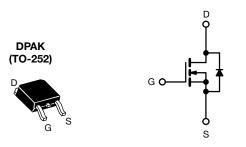
Vishay Siliconix

# **E Series Power MOSFET**

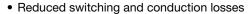


N-Channel MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V) at T <sub>J</sub> max.	850		
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	2.38	
Q <sub>g</sub> max. (nC)	90		
Q <sub>gs</sub> (nC)	11		
Q <sub>gd</sub> (nC)	19		
Configuration	Single		

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)



- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>



### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION		
Package	DPAK (TO-252)	
Lead (Pb)-free and halogen-free	SiHD2N80E-GE3	

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V <sub>DS</sub>	800	V
Gate-source voltage			V <sub>GS</sub>	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous drain surrent (T = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C		2.8	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	1.8	Α
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	5	
Linear derating factor				0.5	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	14	mJ
Maximum power dissipation			P <sub>D</sub>	62.5	W
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
ain-source voltage slope T <sub>J</sub> = 125 °C		dV/dt	70	V/ns	
Reverse diode dV/dt <sup>d</sup>		av/at	0.13	V/IIS	
Soldering recommendations (peak temperature) c For 10 s			300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 0.9 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , dI/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	2.0	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		800	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	1.0	-	V/°C
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Cata assuras lagicara	1		V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 1	μΑ
Zava sata valta sa duais a comant		V <sub>DS</sub> =	V <sub>DS</sub> = 800 V, V <sub>GS</sub> = 0 V		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 640 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 1.0 A	-	2.38	2.75	Ω
Forward transconductance	9 <sub>fs</sub>	$V_{DS}$	= 30 V, I <sub>D</sub> = 1.0 A	-	1.0	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	315		
Output capacitance	C <sub>oss</sub>		$V_{DS} = 100 \text{ V},$	-	20	-	1
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		ı	6	-	1
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	13	-	pF
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	45	-	
Total gate charge	Qg			ı	9.8	19.6	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	V <sub>GS</sub> = 10 V		2.4	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	3.9	-	
Turn-on delay time	t <sub>d(on)</sub>			-	11	22	
Rise time	t <sub>r</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 1.0 A,		-	7	14	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>DD</sub> -	= 10 V, $R_0 = 9.1 \Omega$	-	19	38	ns
Fall time	t <sub>f</sub>			-	27	54	
Gate input resistance	$R_g$	f = 1 MHz, open drain		1.8	3.6	7.2	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.8	
Pulsed diode forward current	I <sub>SM</sub>			-	-	5	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 1 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	278	556	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 1.0 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	0.9	1.8	μC
Reverse recovery current	I <sub>RRM</sub>			-	5	-	A

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$  b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

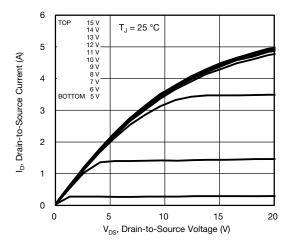


Fig. 1 - Typical Output Characteristics

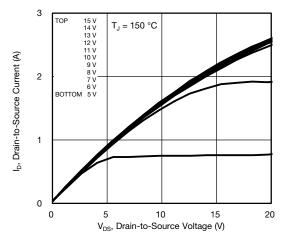


Fig. 2 - Typical Output Characteristics

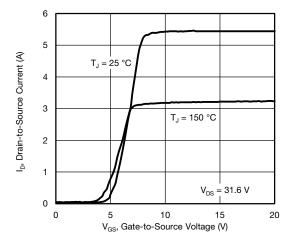


Fig. 3 - Typical Transfer Characteristics

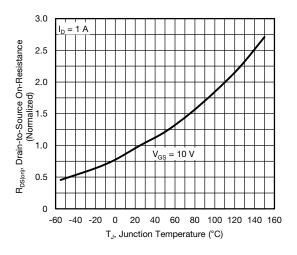


Fig. 4 - Normalized On-Resistance vs. Temperature

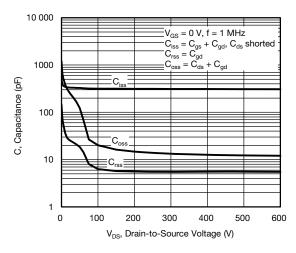


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

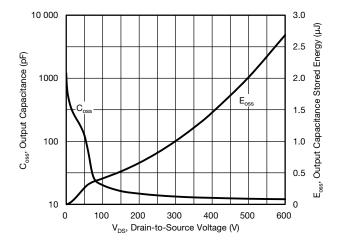


Fig. 6 - Coss and Eoss vs. VDS



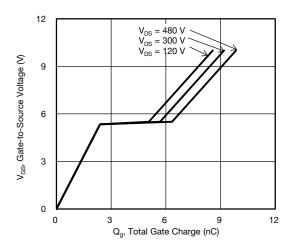


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

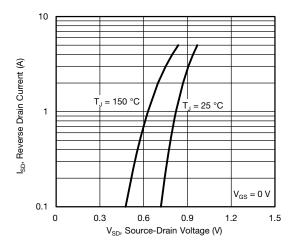


Fig. 8 - Typical Source-Drain Diode Forward Voltage

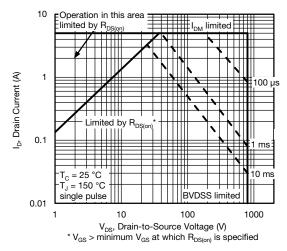


Fig. 9 - Maximum Safe Operating Area

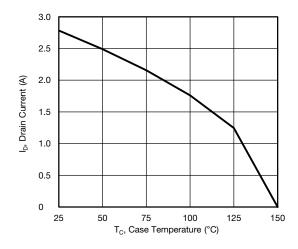


Fig. 10 - Maximum Drain Current vs. Case Temperature

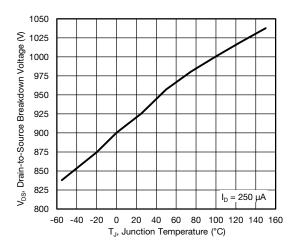


Fig. 11 - Temperature vs. Drain-to-Source Voltage



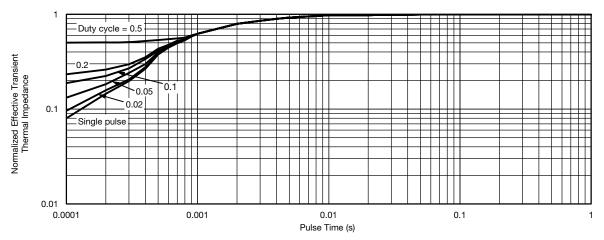


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

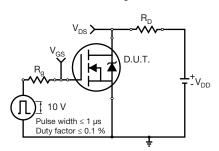


Fig. 13 - Switching Time Test Circuit

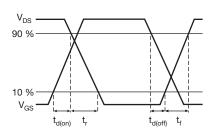


Fig. 14 - Switching Time Waveforms

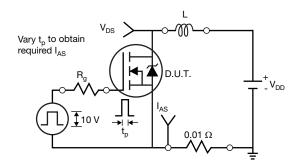


Fig. 15 - Unclamped Inductive Test Circuit

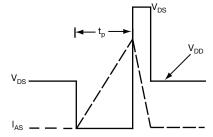


Fig. 16 - Unclamped Inductive Waveforms

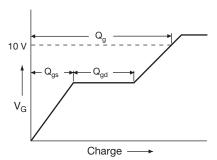


Fig. 17 - Basic Gate Charge Waveform

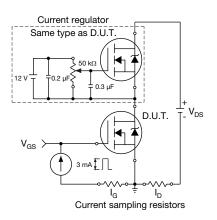
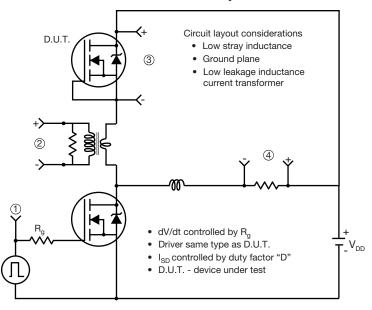


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



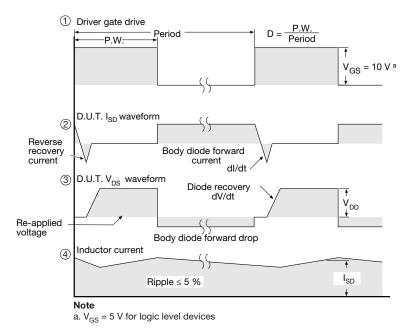


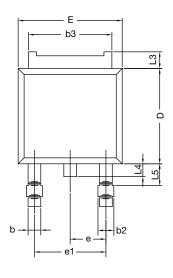
Fig. 19 - For N-Channel

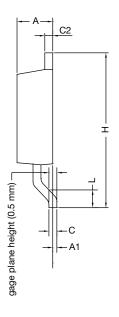
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# **TO-252AA Case Outline**

### **VERSION 1: FACILITY CODE = Y**







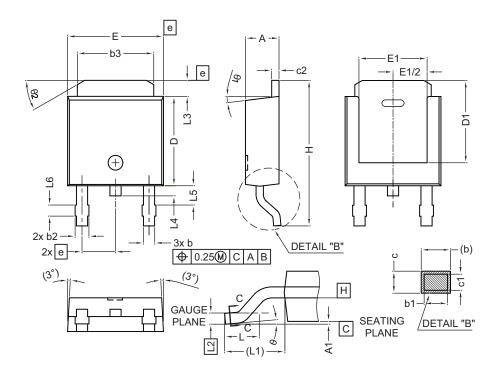
	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28	BSC	
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

### Note

• Dimension L3 is for reference only



### **VERSION 2: FACILITY CODE = N**



	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
E	6.35	6.73	
E1	4.32	-	
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ł ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

### Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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